



We are working on the finishing touches to the COMS 2010 program, it should be complete in the next few weeks. Until then, below are some of the completed sessions we have lined up:

Sessions/Speakers

Cost Analysis and Reverse Engineering/ Teardown of MEMS

Chair	<u>Ron Lawes</u>	MiniFAB (Aus)
<i>Cost Analysis</i>		
Cost Modeling of "MEMS Systems	<u>Scotten Jones</u>	IC Knowledge
MEMS Cost Simulation Tool	<u>Michel Allain</u>	SystemPlus Consulting
Design for Micromanufacturability	<u>Harry Stephanou</u>	UTA ARRI
Cost Analysis - An essential Tool for MEMS Design and Manufacture	<u>Ron Lawes</u>	MiniFAB (Aus)
<i>Tear Down</i>		
Diversity of MEMS Sensor Technologies	<u>Sinjin Dixon-Warren</u>	Chipworks
MEMS Reverse Costing	<u>Michel Allain</u>	SystemPlus
<i>Discussion Panel</i>	<u>Scotten Jones</u>	
	<u>Michel Allain</u>	
	<u>Sinjin Dixon-Warren</u>	

Bio + Nano Tech Commercialization in New Mexico

<i>Session Organizer:</i>	<u>Charles Call</u>	ICx Technologies
Commercialization of NanobioSensors™	<u>Spencer Farr</u>	Vista Therapeutics, Inc.
The DNA Dipstick	<u>John Elling</u>	Mesa Biotech, Inc.
Real-time, Reagentless Identification of Pathogens	<u>Wayne Bryden</u>	ICx Technologies Inc.
Next Generation X-Y Positional Arrays based upon APEX® Glass Ceramic	<u>Jeb H. Flemming</u>	Life BioScience

3-D measurement Metrology

<i>Chair:</i>	<u>Richard Leach</u>	
Critical review of micro-CMM technology	<u>Richard Leach</u>	NPL
Advances in optical 3D micro metrology towards an optical micro CMM	<u>Stephan Scherer</u>	Alicona
Tactile probing on a micro scale	<u>Ernst Treffers</u>	Xpress
Microprobe for coordinate metrology controlled by optical radiation pressure	<u>Yasuhiro Takaya</u>	Osaka University
Measurement of micro gears applying micro coordinate metrology	<u>Ulrich Neuschaefer-Rube</u>	PTB
<i>Panelist:</i>	<u>Herbert Bennett</u>	(NIST)

Packaging & Testing

<i>Chair:</i>	<u>Janusz Bryzek</u>	
Standard Transport Modules for MEMS Testing	<u>Thomas H. Di Stefano</u>	Centipede Systems
MEMS Sensor Package Technology and Migration	<u>Terry Davis</u>	Amkor
TBD	Leland Spangler	Aspen Technologies
3D-WLCSP Packaging Technology for High Volume MEMS Applications	<u>Dan Baldwin</u>	Engent
TBD	<u>John Hunt</u>	ASE
A 3D-WLCSP Technology for MEMS Packaging Applications	<u>Ted Tessier</u>	Flipchip International
The Encapsulation of MEMS/Sensors on package level and wafer level	<u>Ton van Weelden</u>	Boshman
Thin Film Packaging Reinforcement (TFPR): a low cost efficient MEMS packaging	<u>André Rouzaud</u>	CEA Léti
Testing Dynamic Performance of Capacitive MEMS Sensors at Wafer level	Hugh Miller	Solid US Tech

MNT Venture Investment

<i>Chair</i>	<u>Suleiman "Sul" Kassiech</u>	<i>UNM</i>
VC funding of MEMS	JC Eloy	Yole Development
Impact of the global economy on nanotechnology commercialization	<u>Bob Mehalso</u>	Microtec Associates
TBD	<u>Martijn Enter</u>	SEM Ventures
TBD	<u>Brian Birk</u>	Sun Mountain Capital
TBD	<u>John Chavez</u>	New Mexico Angels
TBD	<u>Doug Jamison</u>	Harris and Harris

Nanobiotechnology: Academic, Biotech, Regulatory and Investment Perspectives

Session Chair	<u>Mostafa Analoui, PhD</u>	The Livingston Group
Panel Members:	Vicki Seyfert-Margolis, PhD	US Food and Drug Administration
	<u>Doug Jamison,</u>	Harris & Harris
	<u>Joesph Wang, PhD</u>	University of California, San Diego
	<u>Thomas Schluep, Sc.D.</u>	Calando Pharmaceuticals